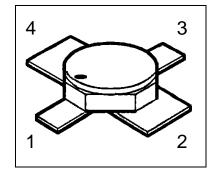


HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain broadband amplifiers at collector currents from 2mA to 30mA.
- Hermetically sealed microwave package
- f_T= 8 GHz
 F = 2.3 dB at 2 GHz
- Space Qualified

ESA/SCC Detail Spec. No.: 5611/006

Type Variant No. 05



ESD: Electrostatic discharge sensitive device, observe handling precautions!

Туре	Marking	Ordering Code	Pin Configuration		Package		
BFY183 (ql)	-	see below	С	Е	В	Е	Micro-X1

(ql) Quality Level: P: Professional Quality

H: High Rel Quality

S: Space Quality

ES: ESA Space Quality

(see order instructions for ordering example)



Maximum Ratings					
Parameter	Symbol	Values	Unit		
Collector-emitter voltage	V_{CEO}	12	V		
Collector-emitter voltage, V _{BE} =0	V _{CES}	20	V		
Collector-base voltage	V_{CBO}	20	V		
Emitter-base voltage	V_{EBO}	2	V		
Collector current	I _C	65	mA		
Base current	I _B	5 ^{1.)}	mA		
Total power dissipation, $T_S \leq 99^{\circ}C^{-2.)}$	P _{tot}	450	mW		
Junction temperature	Tj	200	°C		
Operating temperature range	T _{op}	-65+200	°C		
Storage temperature range	T_{stg}	-65+200	°C		
Thermal Resistance	•	•			
Junction-soldering point ^{2.)}	R _{th JS}	< 225	K/W		

Notes.:

Electrical Characteristics

at T_A=25°C; unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-base cutoff current	I _{CBO}	-	-	100	μA
$V_{CB} = 20 \text{ V}, I_{E} = 0$					
Collector-emitter cutoff current	I _{CEX}	-	-	300	μA
$V_{CE} = 12 \text{ V}, I_{B} = 0.3 \mu A$ 1.)					
Collector-base cutoff current	I _{CBO}	-	-	50	nA
$V_{CB} = 10 \text{ V}, I_{E} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	25	μΑ
$V_{EB} = 2 \text{ V}, I_{C} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μΑ
$V_{EB} = 1 \text{ V}, I_{C} = 0$					

Notes:

 $[\]overline{\ \ \ }$ The maximum permissible base current for V_{FBE} measurements is 20mA (spot-measurement duration < 1s)

²⁾ T_S is measured on the collector lead at the soldering point to the pcb.

^{1.)} This Test assures V(BR)CE0 > 12V



Electrical Characteristics (continued)

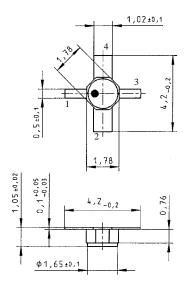
Parameter	Symbol	Values	6	Unit	
		min.	typ.	max.	
DC Characteristics		•	•	•	
Base-Emitter forward voltage	V_{FBE}	-	-	1	V
$I_E = 30 \text{ mA}, I_C = 0$					
DC current gain	h _{FE}	55	90	160	-
$I_C = 5 \text{ mA}, V_{CE} = 6 \text{ V}$					
AC Characteristics					
Transition frequency	f _T				GHz
I_C = 20 mA, V_{CE} = 5 V, f = 500 MHz		6,5	7.5	-	
$I_C = 25 \text{ mA}, V_{CE} = 8 \text{ V}, f = 500 \text{ MHz}$		-	8	-	
Collector-base capacitance	ССВ	-	0.32	0.44	pF
$V_{CB} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C _{CE}	-	0.34	-	pF
$V_{CE} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Emitter-base capacitance	C _{EB}	-	1.1	1.4	pF
$V_{EB} = 0.5V$, $V_{CB} = vcb = 0$, $f = 1 \text{ MHz}$					
Noise Figure	F	-	2.3	2.9	dB
I_C = 8 mA, V_{CE} = 5 V, f = 2 GHz, Z_S = Z_{Sopt}					
Power gain	Gma 1.)	12.5	14	-	dB
$I_C = 20$ mA, $V_{CE} = 5V$, $f = 2$ GHz					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					
Transducer gain	$\left S_{21e}\right ^2$	9	10,5	-	dB
$I_C = 20$ mA, $V_{CE} = 5$ V, $f = 2$ GHz					
$Z_S = Z_L = 50 \Omega$					
Output Power	P _{OUT}	13.5	14.5	-	dBm
I_C = 30 mA, V_{CE} = 5 V, f = 2GHz , P_{IN} =7dBm					
$Z_S = Z_L = 50 \Omega$					

Notes.:

1)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



Micro-X1 Package



Edition 2011-02
Published by
Infineon Technologies AG
85579 Neubiberg, Germany
© Infineon Technologies AG 2011
All Rights Reserved.

Attention please!

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of an third party.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.